AMENDMENTS TO THE CLAIMS:

Claim 1. (Previously Presented) An electronic connector, comprising:

heat generating electronic components, said components comprising a photo-diode and a laser; and

a housing, which is molded over said heat generating electronic components; said molded housing having a first port and a second port for receiving cables fitted with complementary plugs; said housing being made of a thermally conductive material; said thermally conductive material being a net-shape injection moldable polymer composition with a base matrix of liquid crystal polymer material loaded with thermally conductive filler and having a thermal conductivity of at least 30 W/m°k; said housing being in thermal communication with said heat generating electronic components with heat dissipating from said heat generating electronic components and through said housing.

Claim 2. (Canceled)

Claim 3. (Canceled)

Claim 4. (Canceled)

Claim 5. (Canceled)

Claim 6. (Original) The electronic connector of Claim 1, wherein said electronic connector is an opto-electronic connector interface between fiber optic cable and electronic cable.

Claim 7. (Canceled)

Claim 8. (Previously Presented) The electronic connector of Claim 1, wherein said thermally conductive filler is selected from the group consisting of carbon fiber, aluminum, copper, boron nitride, alumina, magnesium and brass.

Claim 9. (Canceled)

Claim 10. (Canceled)

Claim 11. (Currently Amended) A method of forming an electronic connector, comprising the steps of:

providing heat generating electronic components, said components comprising a photo-diode and a laser; and

overmolding an outer housing of injection moldable thermally conductive polymer material, ~~with a base matrix of liquid crystal polymer with filler therein~~ said thermally conductive material being a net-shape injection moldable polymer composition with a base matrix of liquid crystal polymer material loaded with thermally conductive filler and having a thermal conductivity of at least 30 W/m°k, over and around said heat generating electronic components to form an electronic connector having a molded housing with a first port and a second port for receiving cables fitted with complementary plugs, said housing being in thermal communication with said heat generating electronic components with heat dissipating from said heat generating electronic components and through said housing.

Claim 12. (Canceled)

Claim 13. (Previously Presented) The method of Claim 11, wherein said filler is thermally conductive and selected from the group consisting of carbon fiber, aluminum, copper, boron nitride, alumina, magnesium, nickel and brass.

Claim 14. (Canceled)

Claim 15. (Previously Presented) The method of Claim 11, wherein said filler material shields electromagnetic waves and is selected from the group consisting of aluminum, copper, alumina, magnesium and brass.

Claim 16. (Canceled)

Claim 17. (Canceled)

Claim 18. (Canceled)

Claim 19. (Canceled)

Claim 20. (Canceled)

Claim 21. (Canceled)

Claim 22. (Canceled)

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